Fabrication of quantum point contacts by engraving G aA s/A IG aA s-heterostructures with a diam ond tip

J. Regul, U. F. Keyser, M. Paesler, F. Hohls, U. Zeitler, and R. J. Haug Institut fur Festkorperphysik, Universitat Hannover, 30167 Hannover, Germany

A. Malave and E. Oesterschulze

Institut fur Technische Physik, Universitat Kassel, 34132 Kassel, Germany

D.Reuter and A.D.W jeck

Lehrstuhl fur Angewandte Physik, Ruhr-Universitat Bochum, 44780 Bochum, Germany

(D ated: M arch 22, 2024)

W e use the all-diam ond tip of an atom ic force m icroscope for the direct engraving of high-quality quantum point contacts in G aA s/A IG aA s-heterostructures. The processing time is shortened by two orders of magnitude compared to standard silicon tips. Together with a reduction of the line width to below 90 nm, the depletion length of insulating lines is reduced by a factor of two with the diam ond probes. The such fabricated defect-free ballistic constrictions show well-resolved conductance plateaus and the 0.7 anom aly in electronic transport m easurem ents.

PACS num bers: 73.23 A d,73.61 E y,81.16 N d,68.37 P s

O ver the last years the atom ic force m icroscope (AFM) has been used as a exible nanolithographic tool for the direct patterning of surfaces [1]. It o ers not only a convenient and simple way to fabricate sub-m icron devices but also perm its in situ control of relevant sam ple param - eters during the lithography process [2]. A successful and straightforw ard m ethod is the m echanical m anipulation of sem iconductors surfaces by m eans of an AFM -tip. The feasibility of this technique has been demonstrated for various m aterials like G aSb [3], InAs [4] and G aAs [2, 5].

Here we present the application of the engraving technique to fabricate quantum point contact devices in G aA s/A IG aA s-heterostructures. W e show that new alldiam ond tips are ideally suitable for the manufacturing of defect-free ballistic channels in two-dimensional electron gases. We consider the importance of the AFM-tip m aterial by comparing the device properties of sam ples patterned by a silicon tip and by a diam ond tip. Because of its highest possible M ohs hardness of 10 diam ond represents the ideal tip m aterial for the engraving. For the patterning we use standard silicon tips [6] and all-diam ond AFM -tips with force constants of m ore than 40 N/m. The latter were grown by hot-lam ent chem ical vapor deposition of polycrystalline diam ond onto a prepatterned silicon substrate. Details on the fabrication technique are given in [7].

The sam ples presented in this experiment are based on a modulation doped G aA s/A IG aA sheterostructure containing a two-dimensional electron gas (2D EG) 57 nm below the sam ple surface with a sheet density of $4.07 \ 10^{15} \text{ m}^2$ and a mobility of $107 \ \text{m}^2/\text{V}$ s, the layer sequence is shown in Fig.1 (a). We fabricated H allbar geometries with standard photolithography, wet-chem ical etching and alloyed Au/Ge-contacts. A flerwards the sam ples were bonded and mounted into the AFM for the controlled engraving process. For the scribing the AFM -tip is repeatedly scanned over the H all bar with a

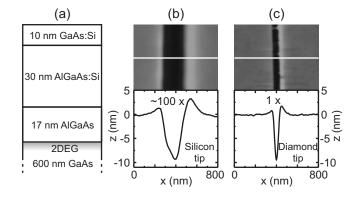


FIG.1: (a) Layer sequence of the heterostructure. The doping concentration of the two upper layers is $0.9 \ 10^{24} \text{ m}^{-3}$. (b)+ (c) Results of the engraving with (b) a silicon tip and (c) a diam ond tip. Upper part: AFM m icrograph of the grooves. Lower part: depth pro le along the white lines. (b) A fter 100 scans with a silicon tip, (c) after one scan with a diam ond tip.

scanning speed of 0.1 mm/s and a contact force of several tens N. Due to this high loading force each scan removes some material of the cap layer which leads to a stepwise depletion of the underlying 2DEG. During the whole lithography procedure the sample resistance is monitored to control the fabrication progress. The total depopulation of the 2DEG is marked by an abrupt raise of the sample resistance to more than 3 M. For more details on our patterning procedure see Ref. [2].

In Fig. 1 (b) we show an AFM -im age of an engraved line that was scribed with a Sitip by applying 50 N as loading force and scanning the tip 100 times over the surface. The resulting line has a width of 250 nm. The depth z 9 nm su ces for this heterostructure for the total depletion of the 2DEG underneath the groove.

W e achieve much narrower lines of 90 nm width and the same depth z 9 nm by using an all-diam ond probe as shown in Fig. 1 (c). The displayed groove was manufactured by scanning the diam ond tip once over the surface with a similar contact force as for Si. Compared to the form er results in Fig. 1 (b) the engraving process for e.g. a 100 m line is substantially reduced by nearly two orders of m agnitude from m inutes to a few seconds. The reduction of the line width from 250 nm to 90 nm is mainly explained by the severe tip wear of the Sitip during the writing process. A fter the engraving we measured the radius of the Sitip and the diam ond tip by scanning electron m icroscopy. W hereas the Sitip radius increased by a factor of 10 to m ore than 100 nm, in ages of the diam ond tips yielded a radius of below 50 nm before and after the fabrication. As expected the tip wear for diam ond is alm ost negligible. In fact, we used this diam ond tip for the fabrication of more than 40 devices without any observation of tip degradation. In contrast, a silicon tip can only be utilized once in most cases.

To compare the electronic properties of the lines fabricated by the di erent tips we de ned two 1D channels by engraving constrictions into the G aA s/A IG aA sheterostructure. The regions separated from the constriction by an insulating groove serve as in-plane gates. The upper insets of Fig. 2 (a) and Fig. 2 (b) show the constrictions engraved with the diam ond tip and (b) the Sitip. B oth constrictions were electrically characterized in a pumped ³H e-cryostat providing a base temperature of T = 350 m K.

In Fig.2 the di erential conductance $G = dI=dV_{SD}$ of the diam ond (a) and the silicon-patterned sample (b) is shown. For the measurem ent we used a standard lock-in technique at an excitation voltage of V_{SD} ; ac = 60 V at 13 Hz. The two conductance curves presented in Fig.2 were recorded by varying only a single in-plane gate whereas the second gate was kept at a xed potential. A constant series resistance of the contacts and the 2DEG was subtracted. A schem atic picture of the measurem ent setup is shown in the lower inset of Fig.2 (b).

The curve in Fig.2(a) corresponding to the diam ondpatterned sample shows at quantized plateaus at multiple integers of $2e^2=h$. This indicates the form ation of a ballistic quantum point contact [8] formed by an adiabatic potential without any in purifies. The appearance of the conductance plateaus dem onstrates that the grooves scribed with the diam ond tip de ne a sm ooth potential without signi cant uctuations. In contrast, the conductance of the silicon-patterned sample, shown in Fig.2(b), exhibits only a few poorly resolved conductance plateaus.

For further characterization of the diam ond-patterned sample we applied an additional dc source-drain bias voltage V_{SD} that allows us to determ ine the 1D-subband spacing [9]. The transconductance dG=dV_{IPG} derived numerically from these measurements is plotted as a function of V_{IPG} and V_{SD} in the grey scale plot in Fig. 3(a). The corresponding conductance is given by

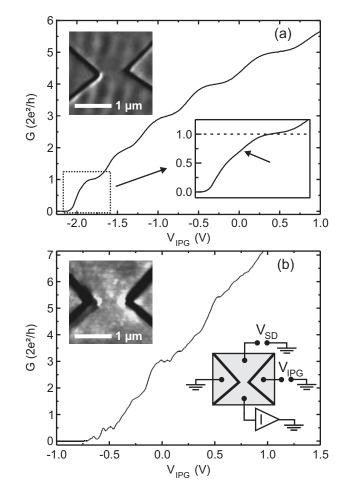


FIG. 2: Dierential conductance G ($V_{\rm IPG}$) = dI= $dV_{\rm SD}$ in units of $2e^2$ =h as a function of in-plane gate voltage: (a) Sam – ple patterned by a diam ond tip. Left inset: A FM –im age of a constriction form ed by a diam ond tip. R ight inset: M agnication of the rst conductance step. The arrow m arks the 0.7 anom aly. (b) Silicon-patterned sam ple. Left inset: A FM – im age of a Sipatterned constriction. The schem atic on the right sketches the m easurem ent setup.

the numbers inside the dark regions and the diam onds for $G = 4(2e^2=h)$ and $G = 5(2e^2=h)$ are marked with dashed lines. The crossing of adjacent zero-bias peaks N and N + 1 at nite bias eV_{SD} reveals the energy spacing E $_{N,N+1}$ = eV_{SD} ranging from E $_{2,3}$ = 2:5(0:1) meV for the second and third subbands to $E_{4:5} = 2:3(0:1) \text{ meV}$. W hereas the subband spacing in split gate devices at higher subband indices drastically decreases we observe only a slight reduction for our sam ple at N > 1. This indicates that the shape of con nement inside the constriction remains nearly una ected by the gate voltage and is only shifted up and down. Assuming a harmonic con nement potential and a gate voltage dependent potential barrier we deduce a value of W 160 nm for the electronic width of the constriction at zero gate voltage with ve occupied subbands. The depletion length for the diam ond tip then can be deter-

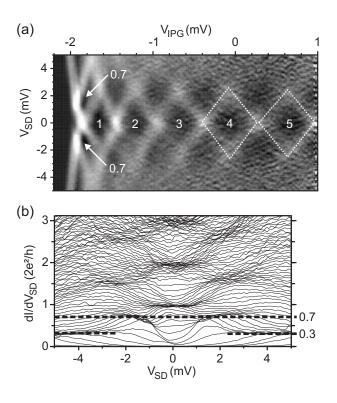


FIG. 3: (a) G rey-scale plot of the transconductance $dG = dV_{IPG}$ obtained from the diam ond-patterned sam ple at a tem perature of T = 350 mK. The gate con guration is the same as in Fig.2 (b). D ark regions correspond to low transconductance (plateaus) and light regions re ect high transconductance (plateau transitions). The num bers denote the occupied subbands. The location of the 0.7 plateaus is marked by the arrows. (b) D i erential conductance as a function of dc source-drain voltage taken at xed gate voltages. The additional plateaus at 0.7 are marked by a dashed line.

m ined to w_{dep1} 180 nm which nearly is half the length of w_{dep1} 330 nm extracted for the silicon-patterned sample. The larger depletion length of the silicon tip as well as the creation of signi cant potential uctuations

3

are probably related to an enhanced form ation of surface defects caused by the increased number of scans.

By inspection of the rst conductance step in the right inset of Fig. 2 (a) we observe an additional shoulder close to 0.7 $(2e^2=h)$. In the grey scale plot in Fig. 3(a) this shoulder leads to additional plateaus for nite bias voltages at $G < 2e^2 = h m$ arked with arrow s. This can be seen m ore clearly in Fig.3(b), where we plotted $G = dI = dV_{SD}$ as a function of dc source-drain voltage taken at xed gate voltages. W hereas the majority of the plateaus appear at multiples of $2e^2 = h$, below $2e^2 = h$ extra plateaus appear at $0.3(2e^2=h)$ and $0.7(2e^2=h)$ m arked by the horizontal dashed line. The so-called 0.7 anom aly [10] is an indicator for very clean one-dimensional channels and is considered to be caused by electron-electron interactions. The exact underlying mechanism of this structure is still. not clari ed but it is an intrinsic property of low -disorder quantum point contacts. Together with the well-resolved plateaus the appearance of the 0.7 anom aly shows that we scribed an adiabatic-like constriction free from significant potential uctuations with the diam ond tip.

In conclusion, we fabricated quantum point contact devices by engraving a constriction into a G aA s/A IG aA sheterostructure with the tip of an atom ic force m icroscope. To study the in uence of the tip material we engraved devices using both a silicon tip and a diam ond tip. It turned out that a diam ond tip is almost perfect not only on the basis of a fast and simple processing but also in forming proper potential pro les to observe ballistic electron transport. The appearance of the 0.7 (2e²=h) conductance anom aly con m s the highquality of diam ond-engraved devices. We deduced the depletion lengths induced by the di erent tips yielding 180 nm for diam ond-engraved sam ples which is Wdepl roughly two times smaller than typical depletion lengths in silicon-patterned devices.

W e thank P.Hullmann for his assistance with the scanning electron m icroscope. This work was supported by the BM BF.

- [L] see e.g., A. Fuhrer, S. Luscher, T. Ihn, T. Heinzel, K. Ensslin, W. Wegscheider, and M. Bichler, Nature 413, 822 (2001).
- [2] H.W. Schum acher, U.F.Keyær, U.Zeitler, R.J.Haug, and K.Eberl, Appl. Phys. Lett. 75, 1107 (1999).
- [3] R.M agno and B.R.Bennett, Appl. Phys.Lett. 70, 1855 (1997).
- [4] J. Cortes Rosa, M. W endel, H. Lorenz, J. P. Kotthaus, M. Thom as, and H. Kroem er, Appl. Phys. Lett. 73, 2684 (1998).
- [5] C.K.Hyon, S.C.Choi, S.H.Song, S.W.Hwang, M. H.Son, D.Ahn, Y.J.Park, and E.K.Kim, Appl.Phys. Lett. 77, 2607 (2000).
- [6] Tapping-m ode probes m ade by N anosensors.

- [7] A. Malave, K. Ludolph, T. Leinhos, Ch. Lehrer, L. Frey, E. O esterschulze, Applied Physics A, in press.
- [8] For example, see C.W. J.Beenaaker and H.van Houten, in Quantum Transport in Semiconductor Nanostructures, Solid State Physics, Vol. 44, A cademic Press, (1991).
- [9] N.K.Patel, J.T.Nicholls, L.Martin-Moreno, M.Pepper, J.E.F.Frost, D.A.Richtie, and G.A.C.Jones, Phys.Rev.B 44, 13549 (1991).
- [10] K.J.Thom as, J.T.N icholls, M.Y.Simmons, M. Pepper, D.R.Mace, and D.A.R ichtie, Phys. Rev. Lett. 77, 135 (1996).